

#### INVENTOR INFORMATION

Inventor One Given Name:: HIROKAZU  
Family Name:: HONDA  
Postal Address Line One:: C/O NEC CORPORATION  
Postal Address Line Two:: 7-1, SHIBA 5-CHOME, MINATO-KU  
City:: TOKYO  
Country:: JAPAN  
City of Residence:: TOKYO  
Country of Residence:: JAPAN  
Citizenship Country:: JAPAN

#### CORRESPONDENCE INFORMATION

Correspondence Customer Number:: 000466  
Name Line One:: YOUNG & THOMPSON  
Address Line One:: 745 SOUTH 23RD STREET  
Address Line Two:: SECOND FLOOR  
City:: ARLINGTON  
State or Province:: VIRGINIA  
Country:: U.S.A.  
Postal or Zip Code:: 22202  
Telephone:: 703-521-2297  
Fax One:: 703-685-0573  
Fax Two:: 703-979-4709

#### APPLICATION INFORMATION

Title Line One:: MULTILAYER INTERCONNECTION BOARD,  
Title Line Two:: SEMICONDUCTOR DEVICE HAVING THE SAME,  
Title Line Three:: AND METHOD OF FORMING THE SAME AS WELL  
Title Line Four:: AS METHOD OF MOUNTING THE SEMICONDUCTOR  
Title Line Five:: CHIP ON THE INTERCONNECTION BOARD  
Total Drawing Sheets:: 158  
Formal Drawings?: YES  
Application Type:: UTILITY  
Docket Number:: PF-2683/NEC/US/mh

#### REPRESENTATIVE INFORMATION

Representative Customer Number:: 000466

#### PRIOR FOREIGN APPLICATION

Foreign Application One:: 11-284566  
Filing Date:: OCTOBER 5, 1999  
Country:: JAPAN  
Priority Claimed:: YES  
  
Foreign Application Two:: 2000-057767  
Filing Date:: MARCH 2, 2000  
Country:: JAPAN  
Priority Claimed:: YES